

# ICSICT 2024

International Conference on Solid-State  
and Integrated Circuit Technology

Oct. 22-25, 2024

Sheraton Zhuhai Hotel  
Zhuhai, China

<http://www.icsict.com>

Final Call For Papers

The ICSICT-2024 conference is the 17th in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct.22-25, 2024 in Zhuhai, China. All aspects of solid-state devices, circuits and systems, process technologies, materials and other related research are within the scope of the conference. A rich program of contributed and invited presentations will cover the latest advancements in those fields. The presentations will be delivered in both oral and poster sessions, accompanied by a panel discussion on the latest technology issues of interest and various engaging activities. The conference aims to foster ample opportunities for exchanges of technical information and create a stimulating atmosphere for communications among participants. The Excellent Student Paper and the Outstanding Young Scholar Paper Award will be selected and announced during the conference's closing ceremony. Enterprises with relevance to the event are encouraged to join and actively take part in the exhibition.

## PAPER SUBMISSION

Prospective authors are requested to submit **3 pages** camera-ready full length paper in English for proceedings publication. The proceedings will have an IEEE catalogue number and will be collected in EI & IEEE publication database ---- **IEEE X'plore** .

**Deadline for Full-Length Paper Submission: June 30, 2024**

**Notification of Acceptance: Aug.15, 2024**

**On-line submission at: <http://www.icsict.com>**

**About paper submission, please contact:**

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**THE SCOPE AND TOPICS OF THE CONFERENCE** (Papers are solicited in, but not limited to the following areas)

## VLSI Technologies

- Advanced CMOS Logic Devices
- Advanced Process Technologies
- Advanced Interconnect Technologies
- Power Devices Technologies
- 2D Devices & Technologies
- Thin Film Devices and Technologies
- Compound Semiconductor Technologies
- Microwave, Millimeter Wave and Analog
- New Non-Volatile Memory Technologies
- Flash & 3D Memory Technologies
- Optoelectronics and Silicon Photonics
- Sensor, MEMS, and Bioelectronics
- Emerging Semiconductor Materials & Devices
- 3D Integration
- Device Technologies for New Computing Syst
- Advanced & Heterogeneous Packaging
- Logic and Power Device Reliability
- Memory Device Reliability
- Back-End of Line Reliability & ESD
- Device Modeling & Simulation
- Process Modeling & Simulation
- Design & Technology Co-Optimization

## VLSI Circuits & ICCAD

- Digital Module & Circuit
- Analog Module & Circuit
- Mixed-Signal Circuit & ADC/DACs
- RF Module & Circuit
- Memory Circuits
- SoC For IoT and other applications
- Processor & Advanced Computing System
- Efficient AI Circuit
- Wireline and Optical Communication Circuit
- FPGA Circuits
- Advanced Clock
- Signal Processing
- Chip Test and Reliability
- EDA Technology for Circuit Design

## Keynote Speakers



Prof. Z. L. Wang  
Georgia Inst. of Tech  
U.S.A.



Dr. Paul Zenos  
Qualcomm  
U.S.A.



Prof. M. H. Sunwoo  
Ajou Univ.  
Korea



Prof. F. Roozboom  
Twente Univ.  
The Netherlands



Prof. Boris Murmann  
University of Hawaii  
U.S.A.



Prof. Albert Wang  
Univ. of Calif. Riverside  
U.S.A.



Prof. Youngcheol Chae  
Yonsei University  
Korea



Prof. Chengjie Zuo  
USTC  
China

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